

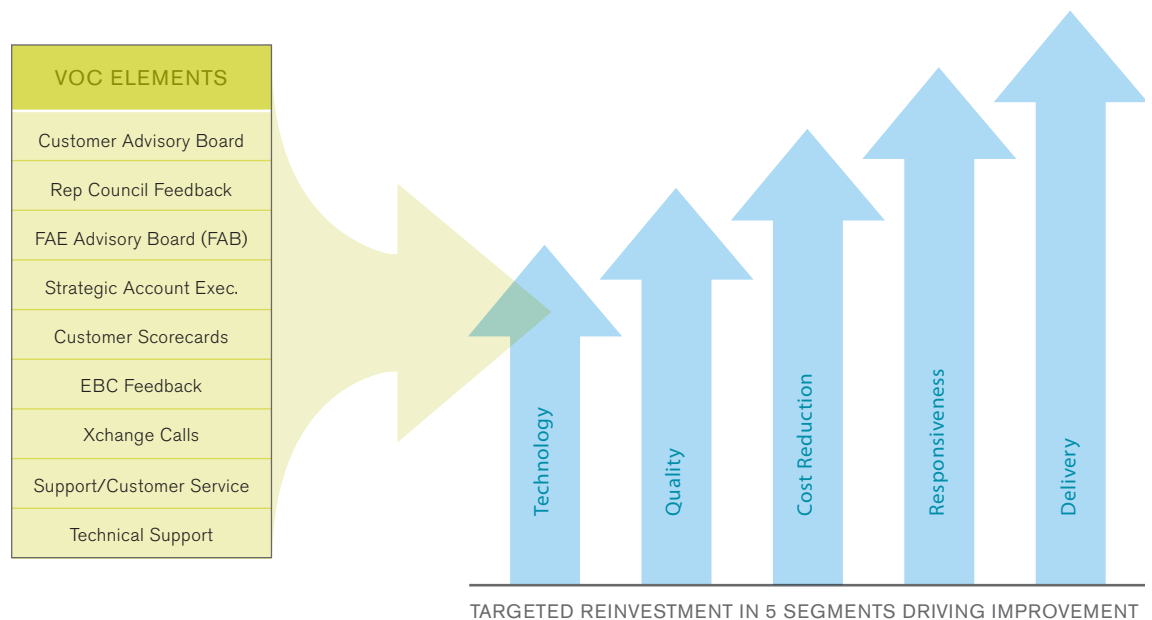
LISTENING TO THE VOICE OF THE CUSTOMER

From the company's first days in business, the Xilinx hallmark has been its exceptional level of customer commitment. Today, our management team recognizes that continued success as an industry-leading semiconductor company depends on the ability to closely listen to and execute customer requirements.

In 2006, Xilinx launched the Voice of the Customer program to formally solicit customer feedback at all levels in the organization, across different vertical markets, and from all corners of the globe. Xilinx engages customers in a variety of ways across different channels, starting at the top with executive sponsorships, customer advisory councils, and strategic account managers. More broadly, a customer survey process relies on real-time feedback mechanisms.

Xilinx uses all of this input to track performance in terms of technology, quality, responsiveness, delivery, and cost metrics (TQRDC). This year, we solicited additional feedback on IP and software to augment the data received through other channels and enable more targeted plans for addressing customers' needs. Based on the favorable customer response to date, Xilinx made additional investments throughout this past year to further automate and expand the Voice of the Customer program.

XILINX QUALITY



Customer-Driven Quality

Quality unites Xilinx employees, suppliers, and stakeholders in a shared mission that puts customers first. The Xilinx executive management team focuses on the quality issues that most affect customers, and the global quality team is engaged in all aspects of the business to drive change where needed for a flawless customer experience.

LISTENING TO THE VOICE OF THE CONSUMER

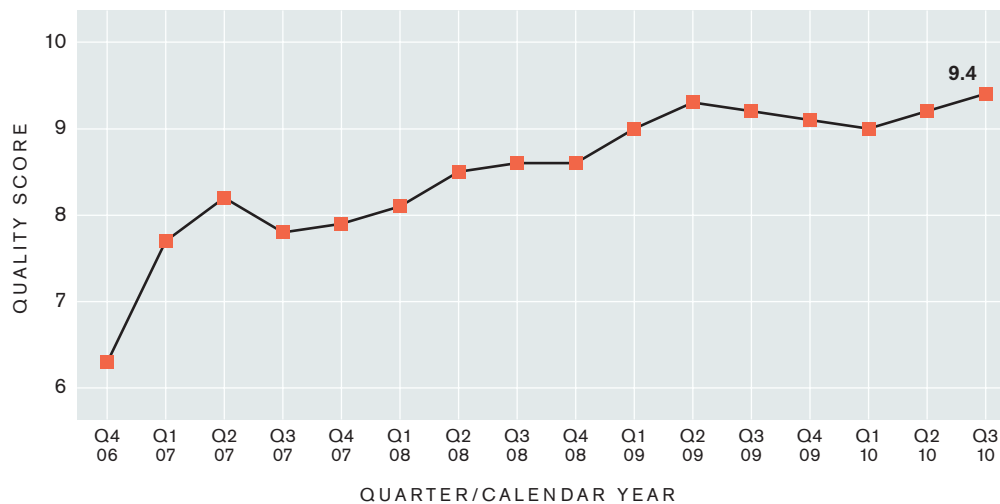
To place priority on the most important aspects of quality and to better understand the root causes of quality issues, Xilinx has instituted a repeatable, closed-loop process that integrates customer interactions from multiple operations within the company to:

- *Understand top issues facing executives and engineers*
- *Analyze data points from a variety of sources*
- *Implement initiatives with metrics for measuring and reporting progress*
- *Validate results with customers directly using a quality-centric scorecard system*

Customer data from scorecards and surveys guides the development of Xilinx quality initiatives. Over time, these programs help Xilinx maintain technology leadership and help customers accelerate quality in the systems they produce for the global customer community.

In 2010, Xilinx achieved all-time-high scores for quality.

Customer Quality Scorecard Data to date



Expanding the Customer Voice

The primary mechanisms for collecting data have been customer scorecards from major accounts, product support surveys, and direct customer interaction. In 2010, Xilinx continues to use the survey process to ensure that more companies are able to provide formal feedback on all aspects of their Xilinx experience—silicon, software, IP, hardware, and support.

Based on the data provided, Xilinx customer-driven quality programs for 2011 are focused on software and IP quality.

To request more information or learn how you can participate in Xilinx's Voice of the Customer program, please contact the quality team at: survey@xilinx.com.

TECHNOLOGY AND CORPORATE LEADERSHIP

Twenty-five years ago, Xilinx invented the FPGA and pioneered the fabless manufacturing model. Since then, Xilinx has led the semiconductor industry by consistently delivering cutting-edge products, technologies, and services, and driving innovation that sets new standards for quality. Below is a sampling of the awards that Xilinx has earned in recent years. They underscore the company's unwavering commitment to customers, as demonstrated by technology excellence and corporate leadership.

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2007-2010 INDUSTRY AWARDS	XILINX RECIPIENT	AWARD SPONSOR
Most Respected Public Fabless Company	Xilinx Corporate	Global Semiconductor Alliance (third award in seven years)
ALICE Industrial Collaboration	Xilinx Corporate	CERN
100 Best Corporate Citizens	Xilinx Corporate	<i>CRO/Business Ethics Magazine</i> (three consecutive years)
Top 25 Microchips that Shook the World	Industry's first FPGA in 1985: Xilinx XC2064FPGA	IEEE Spectrum
Company of the Year Finalist	Xilinx Corporate	<i>EE Times China</i>
LEED Green Building Certification	Xilinx North America HQ	U.S. Green Building Council
ASEAN Energy Awards	Xilinx Asia-Pacific HQ	ASEAN Centre for Energy
PUB Appreciation Certificate	Xilinx Asia-Pacific HQ	Public Utilities Board, Singapore
Universal Design Award for Built Environment (Silver)	Xilinx Asia-Pacific HQ	Singapore Ministry of National Development
Green Mark Platinum Award	Xilinx Asia-Pacific HQ	Singapore Ministry of National Development
Best Product of the Year	Virtex®-5 FXT FPGA	<i>EDN China</i>
Leading Product of the Year	ISE® 10.1 Design Tools	<i>EDN China</i>
Top 10 China Influential Embedded System Finalist	Virtex-5 FXT FPGA MicroBlaze™ v7 Processor AccelDSP™ and System Generator for DSP Tools	EEPW China
Editor's Choice Award	Spartan®-3A FPGA	<i>Portable Design Magazine</i>
Influential Embedded System New Technology Award	Spartan-3A DSP FPGA	EEPW China
Top 10 China Influential Embedded System	Virtex-5 FPGAs	EEPW China
Digital IC Product of the Year	Virtex-5 LXT FPGAs	<i>EDN China</i>
Semiconductor Product of the Year	Virtex-5 LXT FPGA Platform	Elektra Awards
Hot 100 Products	Spartan-3AN FPGA Platform	<i>EDN Magazine</i>
Design Vision Award	PlanAhead™ 8.2 Software	IEC
Product & Innovation of the Year	Virtex-5 FPGA	<i>EDN Magazine</i>
Design Team of the Year	Virtex-5 FPGA Design Team	<i>EDN Magazine</i>
Product of the Year	Virtex-5 FPGA	<i>EE Times China</i>
Ultimate Product Finalist	Virtex-5 FPGA PlanAhead 8.2 Software	<i>EE Times ACE Awards</i>
Most Innovative Product of Year	Virtex-5 FPGA	<i>Electronique Magazine</i>

CUSTOMER SATISFACTION & QUALITY AWARDS	
Anritsu	Top Supplier Award, 2009
Brocade	Quality Excellence Award, 2009
Cisco	Supplier of the Year, 2010
Datang Mobile	Core Partner Award, 2008
General Dynamics	Strategic Supplier Award, 2008
Harman Becker	Top 10 Percent Semiconductor Supplier Award, 2008
Huawei	Core Partner & Most Valued Supplier Awards, 2008 Gold Supplier Award, 2009 Supplier of the Year, 2010
Motorola	Preferred Supplier Award, 2009
Sony	Quality Award, 2008
Spirent	Supplier of the Year, 2008
Tellabs	Perfect 20/20 Quality Score, 2008 Supplier of the Year, 2010
ZTE	Best Supplier Award, 2008-2009 Best Technological Cooperation Award, 2009 Supplier of the Year, 2010

QUALITY RESOURCE GUIDE

Xilinx publishes a comprehensive range of information about its global quality programs, metrics, and documentation. The following tables point to the detailed reports and reference sites, as well as to sites for Xilinx support, training, services, and third-party programs.

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DOCUMENT TITLE	AVAILABILITY
Xilinx Quality	http://www.xilinx.com/products/quality/index.htm
Quality Policy	http://www.xilinx.com/products/quality/Xilinx_Quality_Policy.pdf
Quality Manual	http://www.xilinx.com/products/quality/QualityManual.pdf
Quality Certifications	See links to documentation for each of the following certifications at http://www.xilinx.com/products/quality/index.htm ISO 9001:2008 / TL 9000 (XSJ, XAQ, XIR, XAP), ISO 9001:2008 (XCO), QML per MIL-PRF-38535, ISO 14001:2004 (XSJ), ISO 14001:2004 (XIR), ISO 14001:2004 (XAP), OHSAS 18001:2007 (XIR, XSJ, XAP), MIL-PRF-38535
Annual Quality Reports	http://www.xilinx.com/products/quality/index.htm
Supplier Management	http://www.xilinx.com/products/quality/submgmt.htm
Device Reliability Report (quarterly)	http://www.xilinx.com/support/documentation/user_guides/ug116.pdf
Product Characterization Reports	http://www.xilinx.com/support/documentation/characterization_reports.htm
Silicon Stepping	http://www.xilinx.com/products/quality/silicon-stepping.htm
Pb-Free and RoHS-Compliant Products	http://www.xilinx.com/system_resources/lead_free/
FPGA Design Best Practices	http://www.xilinx.com/products/quality/fpga_best_practices.htm
Product Change Notifications	http://www.xilinx.com/support/documentation/customer_notices.htm
RMA and Returns Instructions	http://www.xilinx.com/products/quality/rma.htm
Qualification Information	A variety of other quality documents, including those listed below, are regularly posted and available on www.xilinx.com . Xilinx Reliability Report, SEU Report, MDDS / IPC-1752 Package Data, ROHS / REACH Declarations

XILINX SITE	DIRECT LINK
Xilinx Home Page	http://www.xilinx.com/
Xilinx Support	http://www.xilinx.com/support/mysupport.htm
Training	http://www.xilinx.com/training/
Documentation	http://www.xilinx.com/support/documentation/index.htm
Downloads	http://www.xilinx.com/support/download/index.htm
Troubleshooting	http://www.xilinx.com/support/troubleshoot.htm
Answer Browser	http://www.xilinx.com/support/answers/index.htm
Forums	http://forums.xilinx.com/xlnx/
Publications	http://www.xilinx.com/publications/
Events	http://www.xilinx.com/events/
Webcasts	http://www.xilinx.com/events/webcasts.htm
Third-Party Alliances	http://www.xilinx.com/alliance/
University Program	http://www.xilinx.com/university/index.htm
Contact Us	http://www.xilinx.com/company/contact.htm

RELIABILITY FAILURE RATE SUMMARY

Failure rates are typically defined in terms of FIT (failure in time) units, where 1 FIT equals 1 failure per 1 billion device hours of operation. For example, 5 failures expected out of 1 million components operating for 1,000 hours means a failure rate of 5 FIT. The failure rate calculation method is summarized below.

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$$\text{Failure Rate} = \frac{X^2 10^9}{2(\text{No. of Devices})(\text{No. of Hours})(\text{Acc. Factor})}$$

Where: X^2 = Chi-squared value at a desired confidence level and $(2f + 2)$ degrees of freedom, where f is the number of failures

The acceleration factor is calculated using the Arrhenius relationship:

$$A = \exp \left\{ \frac{E_a}{k} \cdot \left(\frac{1}{T_{J1}} - \frac{1}{T_{J2}} \right) \right\}$$

Where: E_a = Thermal activation energy (0.7eV is assumed and used in failure rate calculation except for EPROM, in which 0.58eV is used)

A = Acceleration factor

k = Boltzmann's constant, 8.617164×10^{-5} eV/°K

T_{J1} = Use junction temperature in kelvin (°K = °C + 273.16)

T_{J2} = Stress junction temperature in kelvin (°K = °C + 273.16)

PROCESS TECHNOLOGY	DEVICE HOURS AT $T_j = 125^\circ \text{C}$	FIT
0.040 μm	511,947	23
0.045 μm	1,215,891	10
0.065 μm	2,757,393	4
0.09 μm	10,551,344	1
0.13 μm	2,223,135	5
0.15 μm (FPGA)	3,300,458	8
0.15 μm (EPROM)	2,110,352	12
0.18/0.15 μm	2,488,253	10
0.18 μm	3,819,804	14
0.22/0.18 μm	2,057,580	13
0.22 μm	1,959,636	6
0.25 μm	3,082,826	4
0.35 μm / 0.25 μm	2,104,079	5
0.35 μm	4,498,059	15
0.35 μm (EPROM)	1,026,686	24
0.5 μm	2,085,080	12
0.6 μm	813,892	14
0.6 μm (EPROM)	1,054,017	24

1. FIT is calculated based on 0.7eV (0.58eV for EPROM), 60% C.L. and T_j of 55°C.

2. Table contains Q3 CY2010 data. For the most current quarterly report, go to http://www.xilinx.com/support/documentation/user_guides/ug116.pdf

XILINX QUALITY TRENDS

Xilinx continually advances technology to simultaneously increase the levels of quality and innovation. By pioneering new methods, processes, and standards, Xilinx delivers superior solutions with greater efficiency to more than 20,000 customers in diverse global markets.



XILINX QUALITY

QUALITY FOCUS	CALENDAR YEAR 2010 RESULTS	QUALITY IMPROVEMENT FACTORS
Overall Quality	<ul style="list-style-type: none"> ➤ No major customer recalls in more than five years ➤ PPM levels achieving targets ➤ Faster time to market with 40/45nm technologies 	<ul style="list-style-type: none"> ➤ Expanded strong maverick controls ➤ Implemented spatial outlier elimination ➤ Enhanced qualification methodologies earlier in development cycle ➤ Expanded product testing and coverage ➤ Improved new products process and release criteria with each new generation—leveraged learning from 65nm technology
Fab Quality	<ul style="list-style-type: none"> ➤ 65nm defect density: <ul style="list-style-type: none"> ▪ 14% improvement from 2009 ➤ 40nm defect density: <ul style="list-style-type: none"> ▪ 40% improvement from 2009 	<ul style="list-style-type: none"> ➤ Continued improvement of statistical process control ➤ Robust in-line defect reduction ➤ Improved maverick controls
Assembly Quality	<ul style="list-style-type: none"> ➤ Mechanical AOQL PPM achieving targets ➤ Completed RoHs and REACH offerings 	<ul style="list-style-type: none"> ➤ Direct materials control ➤ Failure-mode effects analysis (FMEA) ➤ Commitment to environmentally friendly packaging
Test Quality	<ul style="list-style-type: none"> ➤ Electrical AOQL PPM achieving targets and sustained 0 PPM over multiple quarters ➤ Test coverage at >99% 	<ul style="list-style-type: none"> ➤ Design for test (DFT) ➤ Built-in self-test (BIST) ➤ Software optimization for test ➤ Continued improvement of process control

QUALITY INDUSTRY CERTIFICATIONS

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XILINX FACILITY	QUALITY CERTIFICATION	CERTIFIED SINCE
San Jose, California	TL9000/ISO 9001:2008	January 2004
	ISO/TS16949:2002	March 2005
	ISO 14001:2004	August 2002
	OHSAS18001:2007	October 2008
Dublin, Ireland	TL9000/ISO 9001:2008	January 2004
	ISO/TS16949:2002	March 2005
	ISO 14001:2004	August 1999
	OHSAS18001:2007	October 2008
Singapore	TL9000/ISO 9001:2008	January 2005
	ISO/TS16949:2002	March 2005
	ISO 14001:2004	August 2006
	OHSAS18001:2007	October 2008
Albuquerque, New Mexico	TL9000/ISO 9001:2008	January 2005
	ISO/TS16949:2002	March 2005
Denver, Colorado	ISO9001:2008	December 2004

XILINX SUPPLIERS	QUALITY CERTIFICATION	SUPPLIER RELATIONSHIP
UMC, Hsinchu, Taiwan	ISO9001:2000	Foundry
Toshiba, Japan	TS16949:2002	
Samsung, Korea		
TSMC, Taiwan		
Amkor, Korea	ISO9001:2000	Assembly and Test
Amkor, Phillipines	TS16949:2002	
STATS ChipPAC		
SFIL		